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Dimensions	
L	5.7mm +/-0.4mm
W	10.3mm +/-0.8mm
T	5mm +/-0.4mm
B	0.6mm +/-0.35mm

Packaging Specifications	
Packaging	T&R, 330mm
Packaging Quantity	525

General Information	
Series	KONNEKT KC-LINK Comm COG
Style	KONNEKT
Description	KC-LINK with KONNEKT, SMD, MLCC, Ultra-Stable, Class I
Features	Ultra-Stable
RoHS	Yes
Termination	Tin
AEC-Q200	No
Component Weight	1.4 g
Notes	4-Chip Low Loss Orientation.
Chip Size	2220-4
MSL	1

Specifications	
Capacitance	0.048 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	1200 VDC
Dielectric Withstanding Voltage	1440 VDC
Temperature Range	-55/+150°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	20.8333 GOhms

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